CMPD2005S CMPD2005SG*

SURFACE MOUNT
DUAL, IN SERIES
HIGH VOLTAGE
SILICON SWITCHING DIODES



^{*} Device is *Halogen Free* by design



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMPD2005S and CMPD2005SG each contain two (2) High Voltage Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a SOT-23 surface mount package, designed for applications requiring high voltage capability.

MARKING CODES: CMPD2005S: DB5 CMPD2005SG*: 5SG

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	300	V
Peak Repetitive Reverse Voltage	V_{RRM}	350	V
Average Forward Current	IO	200	mA
Continuous Forward Current	Ι _Ε	225	mA
Peak Repetitive Forward Current	I _{FRM}	625	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	$\Theta_{\sf JA}$	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: $(T_A=25^{\circ}C \text{ unless otherwise noted})$

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =280V		100	nA
I_{R}	V _R =280V, T _A =150°C		100	μΑ
BV_R	I _R =100μA	350		V
V_{F}	I _F =20mA		0.87	V
V_{F}	I _F =100mA		1.0	V
V_{F}	I _F =200mA		1.25	V
c_T	V _R =0, f=1.0MHz		5.0	pF
t _{rr}	$I_R=I_F=30$ mA, Rec. to 3.0mA, $R_L=100\Omega$		50	ns

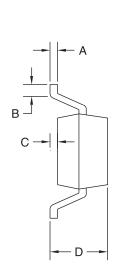
CMPD2005S CMPD2005SG*

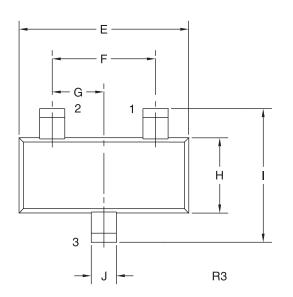
HIGH VOLTAGE SILICON SWITCHING DIODES

SURFACE MOUNT DUAL, IN SERIES

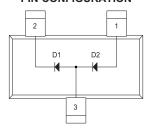


SOT-23 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



LEAD CODE:

- 1) Anode D2
- 2) Cathode D1
- 3) Anode D1, Cathode D2

MARKING CODES: CMPD2005S: DB5

CMPD2005SG*: 5SG

DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.003	0.007	0.08	0.18			
В	0.006	-	0.15	-			
С	-	0.005	-	0.13			
D	0.035	0.043	0.89	1.09			
E	0.110	0.120	2.80	3.05			
F	0.075		1.90				
G	0.037		0.95				
Н	0.047	0.055	1.19	1.40			
	0.083	0.098	2.10	2.49			
J	0.014	0.020	0.35	0.50			

SOT-23 (REV: R3)

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R3 (25-January 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors:

www.centralsemi.com/wwdistributors

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